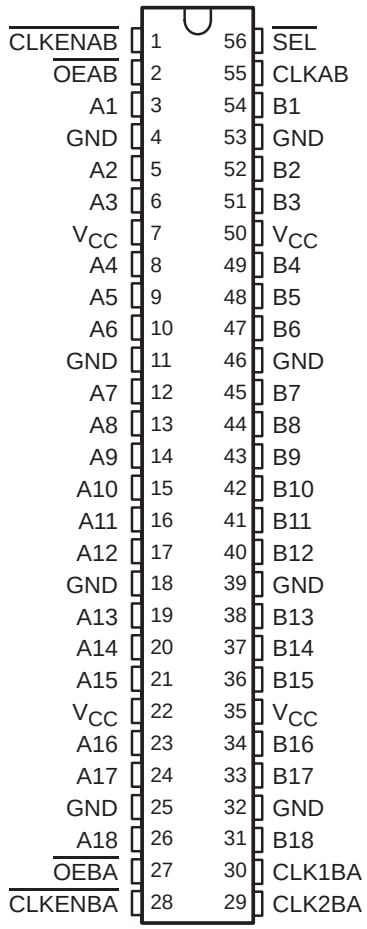
- **Member of the Texas Instruments *Widebus*™ Family**
- ***EPIC*™ (Enhanced-Performance Implanted CMOS) Submicron Process**
- **B-Port Outputs Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 250 mA Per JESD 17**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Package Option Includes Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages**

NOTE: For tape and reel order entry:
The DGGR package is abbreviated to GR.

DGG OR DL PACKAGE
(TOP VIEW)



description

This 18-bit universal bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$) and clock-enable ($\overline{CLKENAB}$ and $\overline{CLKENBA}$) inputs. For the A-to-B data flow, the data flows through a single register. The B-to-A data can flow through a four-stage pipeline register path, or through a single register path, depending on the state of the select ($\overline{SEL}$) input.

Data is stored in the internal registers on the low-to-high transition of the clock (CLK) input, provided that the appropriate $\overline{CLKEN}$ inputs are low. The A-to-B data transfer is synchronized to the CLKAB input, and B-to-A data transfer is synchronized with the CLK1BA and CLK2BA inputs.

The B outputs, which are designed to sink up to 12 mA, include equivalent 26-Ω resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH162525 is characterized for operation from –40°C to 85°C.

Function Tables

A-TO-B STORAGE
($\overline{OEAB}$ = L)

INPUTS			OUTPUT
$\overline{CLKENAB}$	CLKAB	A	B
H	X	X	B_0†
L	↑	L	L
L	↑	H	H

† Output level before the indicated steady-state input conditions were established

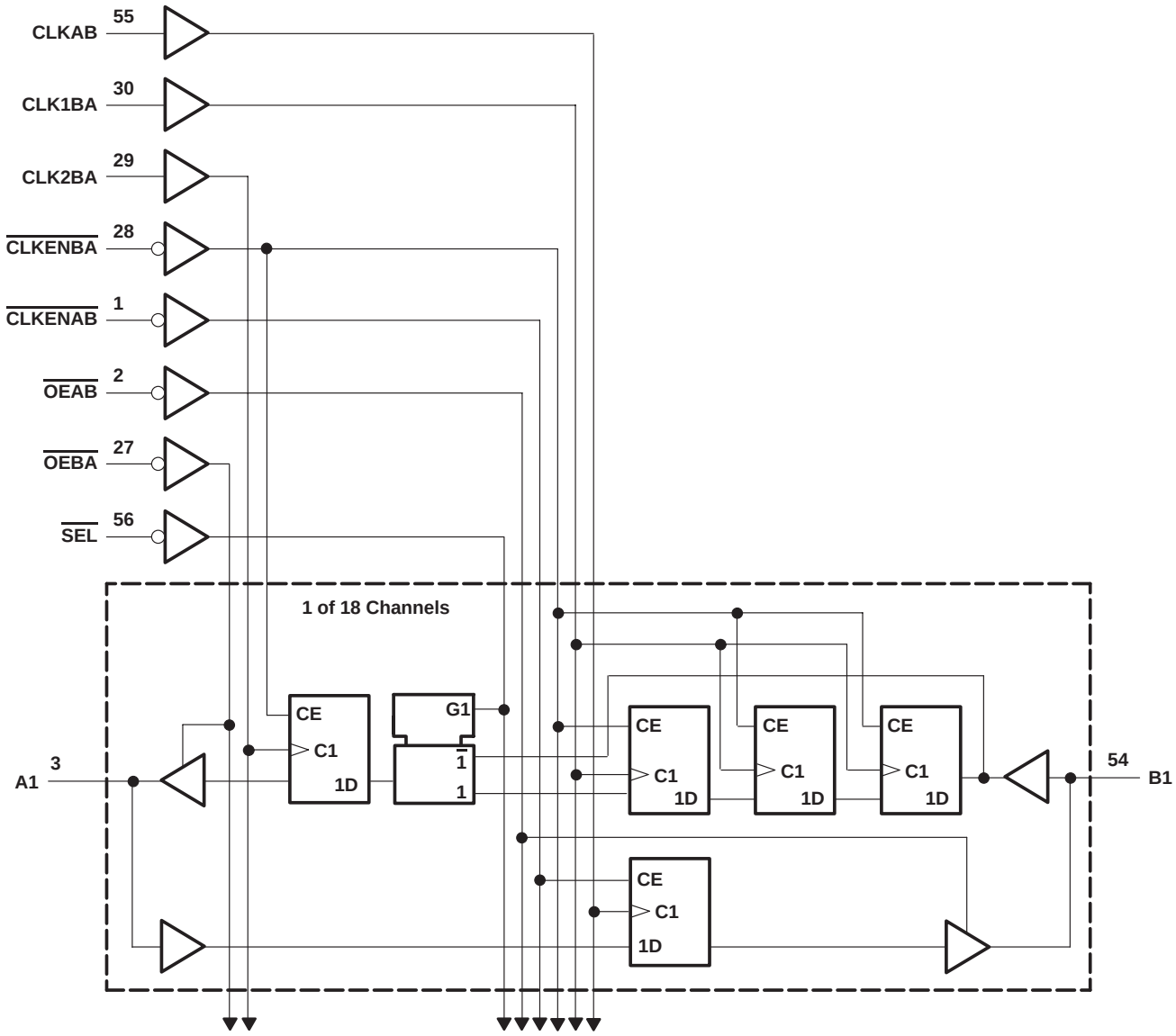
B-TO-A STORAGE
($\overline{OEBA}$ = L)

INPUTS					OUTPUT
$\overline{CLKENBA}$	CLK2BA	CLK1BA	$\overline{SEL}$	B	A
H	X	X	X	X	A_0†
L	↑	X	H	L	L
L	↑	X	H	H	H
L	↑	↑	L	L	L‡
L	↑	↑	L	H	H‡

† Output level before the indicated steady-state input conditions were established

‡ Three CLK1BA edges and one $\overline{CLK}$2BA edge are needed to propagate data from B to A when $\overline{SEL}$ is low.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I: Except I/O ports (see Note 1)	–0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	–0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0)	–50 mA
Output clamp current, I_{OK} (V_O < 0)	–50 mA
Continuous output current, I_O	±50 mA
Continuous current through each V_{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		1.65	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 1.65 V to 1.95 V	0.65 × V_{CC}		V
		V_{CC} = 2.3 V to 2.7 V	1.7		
		V_{CC} = 2.7 V to 3.6 V	2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65 V to 1.95 V		0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V		0.7	
		V_{CC} = 2.7 V to 3.6 V		0.8	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current (A port)	V_{CC} = 1.65 V		–4	mA
		V_{CC} = 2.3 V		–12	
		V_{CC} = 2.7 V		–12	
		V_{CC} = 3 V		–24	
	High-level output current (B port)	V_{CC} = 1.65 V		–2	
		V_{CC} = 2.3 V		–6	
		V_{CC} = 2.7 V		–8	
		V_{CC} = 3 V		–12	
I_{OL}	Low-level output current (A port)	V_{CC} = 1.65 V		4	mA
		V_{CC} = 2.3 V		12	
		V_{CC} = 2.7 V		12	
		V_{CC} = 3 V		24	
	Low-level output current (B port)	V_{CC} = 1.65 V		2	
		V_{CC} = 2.3 V		6	
		V_{CC} = 2.7 V		8	
		V_{CC} = 3 V		12	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature		–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP†	MAX	UNIT
V_{OH}	A port	I_{OH} = –100 µA	1.65 V to 3.6 V	V_{CC}–0.2			V
		I_{OH} = –4 mA	1.65 V	1.2			
		I_{OH} = –6 mA	2.3 V	2			
		I_{OH} = –12 mA	2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
		I_{OH} = –24 mA	3 V	2			
	B port	I_{OH} = –100 µA	1.65 V to 3.6 V	V_{CC}–0.2			
		I_{OH} = –2 mA	1.65 V	1.2			
		I_{OH} = –4 mA	2.3 V	1.9			
		I_{OH} = –6 mA	2.3 V	1.7			
			3 V	2.4			
		I_{OH} = –8 mA	2.7 V	2			
		I_{OH} = –12 mA	3 V	2			
V_{OL}	A port	I_{OL} = 100 µA	1.65 V to 3.6 V			0.2	V
		I_{OL} = 4 mA	1.65 V			0.45	
		I_{OL} = 6 mA	2.3 V			0.4	
		I_{OL} = 12 mA	2.3 V			0.7	
			2.7 V			0.4	
		I_{OL} = 24 mA	3 V			0.55	
	B port	I_{OL} = 100 µA	1.65 V to 3.6 V			0.2	
		I_{OL} = 2 mA	1.65 V			0.45	
		I_{OL} = 4 mA	2.3 V			0.4	
		I_{OL} = 6 mA	2.3 V			0.55	
			3 V			0.55	
		I_{OL} = 8 mA	2.7 V			0.6	
		I_{OL} = 12 mA	3 V			0.8	
I_I		V_I = V_{CC} or GND	3.6 V			±5	µA
$I_{I(hold)}$		V_I = 0.58 V	1.65 V	25			µA
		V_I = 1.07 V		–25			
		V_I = 0.7 V	2.3 V	45			
		V_I = 1.7 V		–45			
		V_I = 0.8 V	3 V	75			
		V_I = 2 V		–75			
		V_I = 0 to 3.6 V‡	3.6 V			±500	
I_{OZ}§		V_O = V_{CC} or GND	3.6 V			±10	µA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	3.6 V			40	µA
ΔI_{CC}		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V			750	µA
C_i	Control inputs	V_I = V_{CC} or GND	3.3 V		3		pF
C_{io}	A or B ports	V_O = V_{CC} or GND	3.3 V		7		pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.
§ For I/O ports, the parameter I_{OZ} includes the input leakage current.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

			V_{CC} = 1.8 V		V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			†		120		125		150	MHz
t_w	Pulse duration, CLK high or low		†		3.2		3.2		3		ns
t_{su}	Setup time	A data before CLKAB↑	†		1.3		1.3		1.3		ns
		B data before CLK2BA↑	†		2.1		1.8		1.7		
		B data before CLK1BA↑	†		1.3		1.2		1.1		
		$\overline{SEL}$ before CLK2BA↑	†		3.3		3.3		3.3		
		$\overline{CLKENAB}$ before CLKAB↑	†		2.1		1.9		1.6		
		$\overline{CLKENBA}$ before CLK1BA↑	†		2.7		2.5		2.1		
		$\overline{CLKENBA}$ before CLK2BA↑	†		2.7		2.5		2.2		
t_h	Hold time	A data after CLKAB↑	†		0.7		0.4		0.9		ns
		B data after CLK2BA↑	†		0.4		0		0.6		
		B data after CLK1BA↑	†		0.8		0.4		1		
		$\overline{SEL}$ after CLK2BA↑	†		0		0		0.1		
		$\overline{CLKENAB}$ after CLKAB↑	†		0.1		0.3		0.3		
		$\overline{CLKENBA}$ after CLK1BA↑	†		0		0		0.1		
		$\overline{CLKENBA}$ after CLK2BA↑	†		0		0		0		

† This information was not available at the time of publication.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 1.8 V		V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			†		120		125		150		MHz
t_{pd}	CLKAB	B		†	1	5.5		5.4	1	4.7	ns
	CLK2BA	A		†	1	4.5		4.4	1	4.2	
t_{en}	$\overline{OEBA}$	A		†	1	6.1		6.1	1	5.1	ns
	$\overline{OEAB}$	B		†	1	6.7		6.8	1	5.7	
t_{dis}	$\overline{OEBA}$	A		†	1	6.3		5.4	1	4.9	ns
	$\overline{OEAB}$	B		†	1	6.3		5.4	1	4.9	

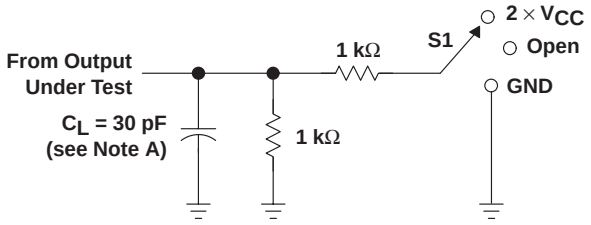
† This information was not available at the time of publication.

operating characteristics, T_A = 25°C

PARAMETER			TEST CONDITIONS	V_{CC} = 1.8 V	V_{CC} = 2.5 V	V_{CC} = 3.3 V	UNIT
				TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF, f = 10 MHz	†	160	160	pF
		Outputs disabled		†	160	160	

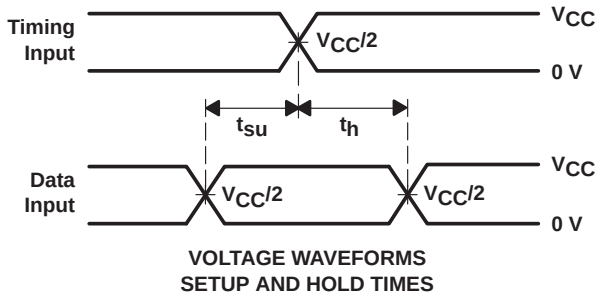
† This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION
V_{CC} = 1.8 V

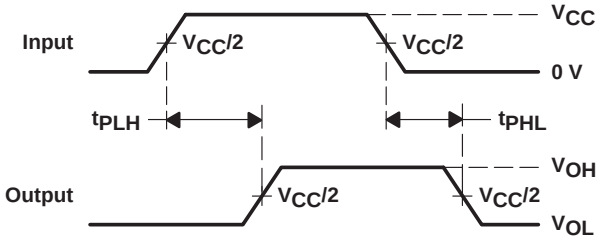


TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

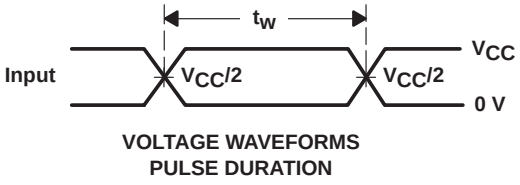
LOAD CIRCUIT



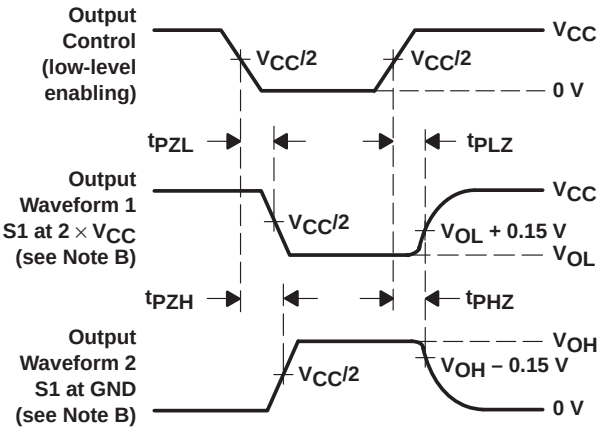
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION

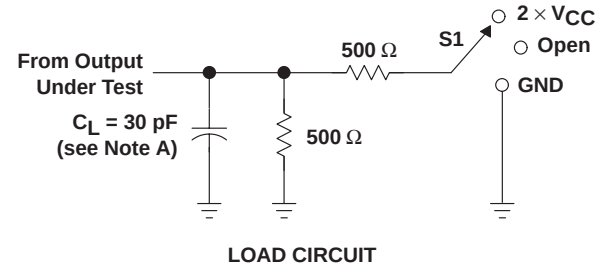


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2 ns, t_f ≤ 2 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

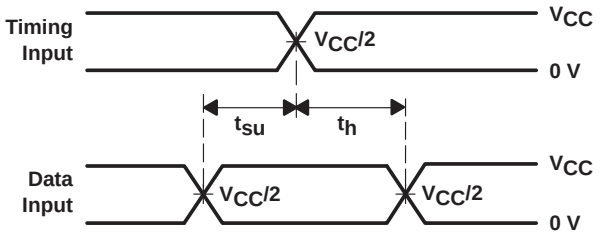
Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION
V_{CC} = 2.5 V ± 0.2 V

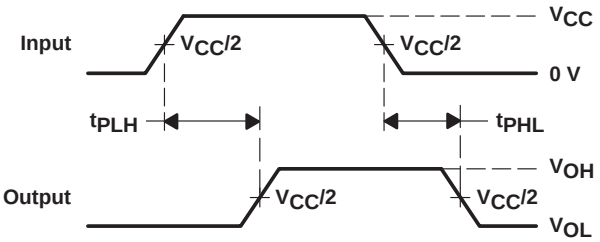


LOAD CIRCUIT

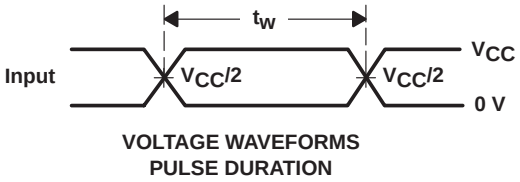
TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open 2 × V_{CC} GND



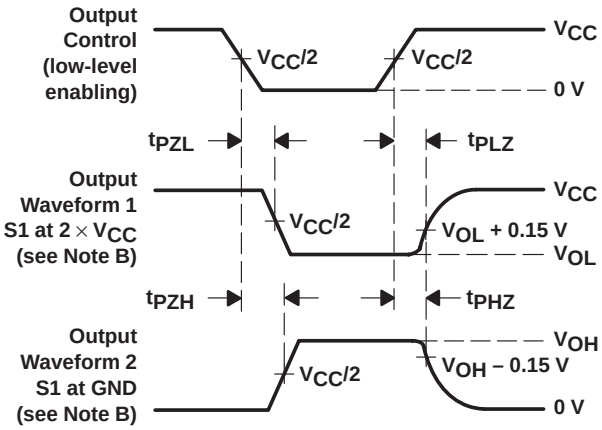
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION

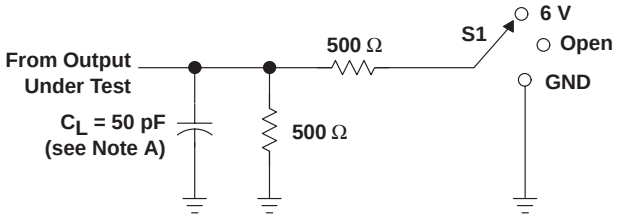


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2 ns, t_f ≤ 2 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

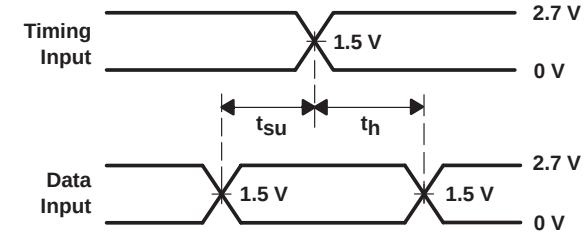
Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION
V_{CC} = 2.7 V AND 3.3 V ± 0.3 V

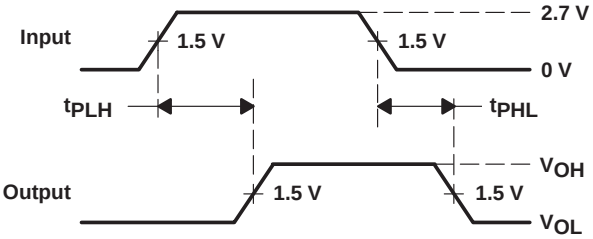


TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

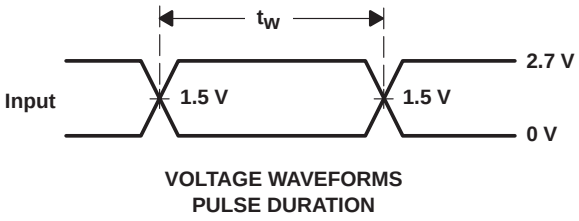
LOAD CIRCUIT



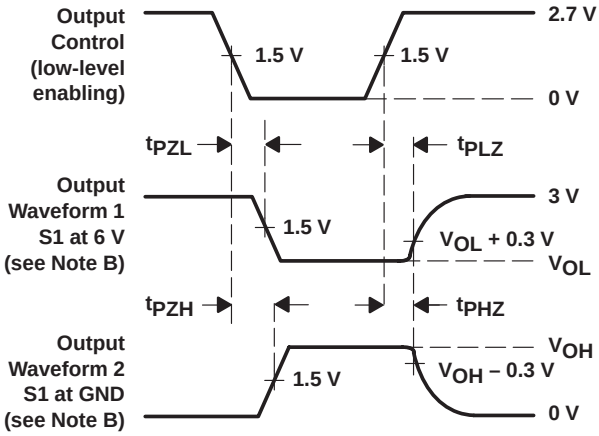
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
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C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 3. Load Circuit and Voltage Waveforms

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